



Material Content Data Sheet



Sales Product Name		IPB038N12N3 G		Issued		19. January 2018		
MA#		MA000800814						
Package		PG-TO263-3-2		Weight*		1567.80 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	17.562	1.12	1.12	11202	11202
leadframe	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	iron	7439-89-6	0.304	0.02		194	
	non noble metal	copper	7440-50-8	304.026	19.39	19.42	193919	194171
	non noble metal	aluminium	7429-90-5	11.738	0.75	0.75	7487	7487
wire	non noble metal	aluminium	7429-90-5	11.738	0.75	0.75	7487	7487
encapsulation	organic material	carbon black	1333-86-4	9.984	0.64		6368	
	plastics	epoxy resin	-	109.826	7.01		70051	
	inorganic material	silicondioxide	60676-86-0	545.803	34.81	42.46	348133	424552
leadfinish	non noble metal	tin	7440-31-5	9.657	0.62	0.62	6159	6159
plating	inorganic material	phosphorus	7723-14-0	0.001	0.00		1	
	non noble metal	nickel	7440-02-0	0.228	0.01	0.01	146	147
solder	non noble metal	tin	7440-31-5	0.204	0.01		130	
	noble metal	silver	7440-22-4	0.255	0.02		163	
	non noble metal	lead	7439-92-1	9.743	0.62	0.65	6214	6507
heatspreader	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	iron	7439-89-6	0.548	0.04		350	
	non noble metal	copper	7440-50-8	547.666	34.92	34.97	349320	349775
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com